

09/531,163

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,740,590 B1
DATED : May 25, 2004
INVENTOR(S) : Yano et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title page, Item [54] and Column 1, lines 1-5,

Title, should read:

**-- AQUEOUS DISPERSION, AQUEOUS DISPERSION FOR CHEMICAL
MECHANICAL POLISHING USED FOR MANUFACTURE OF
SEMICONDUCTOR DEVICES, METHOD FOR MANUFACTURE OF
SEMICONDUCTOR DEVICES, AND METHOD FOR FORMATION OF
EMBEDDED WIRING --**

Signed and Sealed this

Fifteenth Day of February, 2005

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looped initial "J" and a distinct "D" at the end.

JON W. DUDAS
Director of the United States Patent and Trademark Office